

AMENDMENT TO THE CLAIMS

The following listing of claims will replace all prior versions, and listing of claims in the application:

LISTING OF CLAIMS

1. (Currently amended) A structure of memory card comprising:

a base plate on which IC chips are connected;

a case mounted to the base plate and at least one window defined through the case so that at least one of the IC chips is accommodated in the at least one window, a space enclosed by the at least one window being larger than the at least one of the IC chips and a top surface of the at least one of the IC chips accommodated in the at least one window being in flush with a top surface of the case, and

a seal plate attached on the case and sealing the at least one window.

2. (Original) The device as claimed in claim 1, wherein the IC chips have connection legs electrically connected to the base plate.

3. (Cancelled) The device as claimed in claim 1, wherein a top surface of the at least one of the IC chips accommodated in the at least one window is in flush with a top surface of the case.

4. (New) A structure of memory card comprising:

a base plate on which IC chips are connected;

a case mounted to the base plate and at least one window defined through the case so that at least one of the IC chips is accommodated in the at least one window, a space enclosed by the at least one window being slightly larger than the at least one of the IC chips and a top surface of the at least one of the IC chips accommodated in the at least one window being in flush with a top surface of the case, a periphery of the at least one of the IC chips being fitted and in contact with an inner periphery of the at least one window, and

a seal plate attached on the case and sealing the at least one window.